

ABSTRACT

The present invention relates to the field of semiconductor device manufacturing, and in particular to a splash-proofing device for a photoresist stripping process, a photoresist stripping apparatus, and a chemical solution delivery device. The splash-proofing device is disposed inside a chamber and comprises a blocking assembly, an exhaust assembly, a stage, and a nozzle. The stage is used to support a substrate, and the nozzle is positioned above the stage at a preset height. The blocking assembly includes at least one protection plate disposed at the periphery of the substrate for preventing the chemical solution sprayed onto the substrate from splashing into the chamber. The exhaust assembly comprises an exhaust duct and an exhaust hood that are in communication with each other. The exhaust hood is disposed at the periphery of the nozzle, and an exhaust port of the exhaust hood is disposed above the substrate. The exhaust assembly is used to draw splashed atomized chemical solution out of the chamber. The protection plate forms a barrier that efficiently blocks chemical solution splashing, and the exhaust assembly, by suction, draws the atomized chemical solution out of the chamber through the exhaust hood and then the exhaust duct, further preventing chemical solution splashing.